

Application No. 09/676,696

a fiber coupling assembly having a barrel which operably engages a fiber optic cable; and

an alignment guide structure for passively aligning said fiber coupling assembly with said optoelectronic device.

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REMARKS

Applicant has amended claims 1 22, 38, 46 and 47 for clarity and added claims 49-56 to claim additional subject matter to which applicant is entitled. Applicants respectfully request entry of the present amendment and examination and allowance of this application.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted,

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By



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) An optical device package comprising:
an optoelectronic device, comprising a mounting surface
operably coupled to a surface of a substrate and an active surface
that emits or receives light, wherein said active surface of said
optoelectronic device is substantially parallel to said substrate and
[7] wherein said optoelectronic device is in electrical communication
with said substrate; and
an enclosure coupled to said substrate, that houses said
optoelectronic device.

22. (Amended) The optical device package of claim 1 wherein said
optoelectronic device comprises an integrated transceiver, wherein
said transceiver comprises a transmitter, a power monitoring
photodetector and a photodiode [~~reciever~~] receiver.

38. (Amended) The optical device package of claim 1 further
comprising:
a fiber coupling assembly having a barrel which operably
engages a fiber optic cable; and
an alignment guide structure for passively aligning said
fiber coupling assembly with said [~~optical~~] optoelectronic device.

46. (Amended) The optical device package of claim 45 wherein
said substrate [~~is~~] comprises a flex-rigid circuit board, and wherein
said flex-rigid circuit board comprises a daughter board coupled to
a mother board by a flexible substrate.

47. (Amended) A method of packaging an optoelectronic device
comprising the steps of:
operably [~~mounting an~~] coupling a mounting surface of an
optoelectronic device on a surface of a substrate, wherein an active

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surface of said optoelectronic device that emits or receives light is substantially parallel to said substrate surface;

electrically coupling the optoelectronic device to said substrate;

sealing the optoelectronic device.

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